

ON Semiconductor®

FDMS5360L-F085

N-Channel Power Trench[®] MOSFET **60V, 60A, 8.5m**Ω

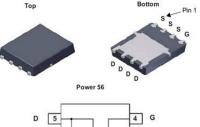
Features

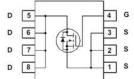
- Typ $r_{DS(on)}$ = 6.5m Ω at V_{GS} = 10V, I_D = 60A
- Typ $Q_{g(tot)}$ = 64nC at V_{GS} = 10V, I_D = 60A
- UIS Capability
- RoHS Compliant
- Qualified to AEC Q101

Applications

- Automotive Engine Control
- Powertrain Management
- Solenoid and Motor Drivers
- Integrated Starter/alternator
- Primary Switch for 12V Systems







MOSFET Maximum Ratings T_J = 25°C unless otherwise noted

Symbol	Parameter		Ratings	Units	
V _{DSS}	Drain to Source Voltage		60	V	
V _{GS}	Gate to Source Voltage		±20	V	
	Drain Current - Continuous (V _{GS} =10) (Note 1)	T _C =25°C	60	•	
D	Pulsed Drain Current	T _C = 25°C	See Figure4	— A	
E _{AS}	Single Pulse Avalanche Energy	(Note 2)	115	mJ	
6	Power Dissipation		150	W	
PD	Derate above 25°C		1	W/ ^o C	
T _J , T _{STG}	Operating and Storage Temperature		-55 to + 175	°C	
$R_{\theta JC}$	Thermal Resistance Junction to Case		1	°C/W	
R _{0JA}	Maximum Thermal Resistance Junction to Ambient	(Note 3)	50	°C/W	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMS5360L	FDMS5360L-F085	Power 56	13"	12mm	3000 units

Notes:

1: Current is limited by junction temperature.

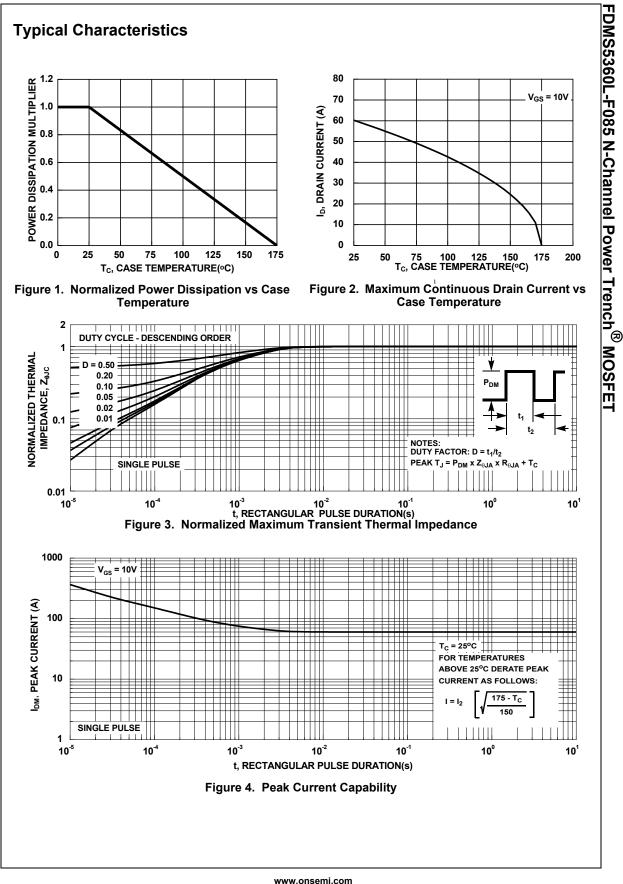
2: Starting $T_J = 25^{\circ}C$, L = 0.1mH, $I_{AS} = 48A$, $V_{DD} = 60V$ during inductor charging and $V_{DD} = 0V$ during time in avalanche 3: $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta,JC}$ is guaranteed by design while $R_{\theta,JA}$ is determined by the user's board design. The maximum rating presented here is based on mounting on a 1 in² pad of 2oz copper.

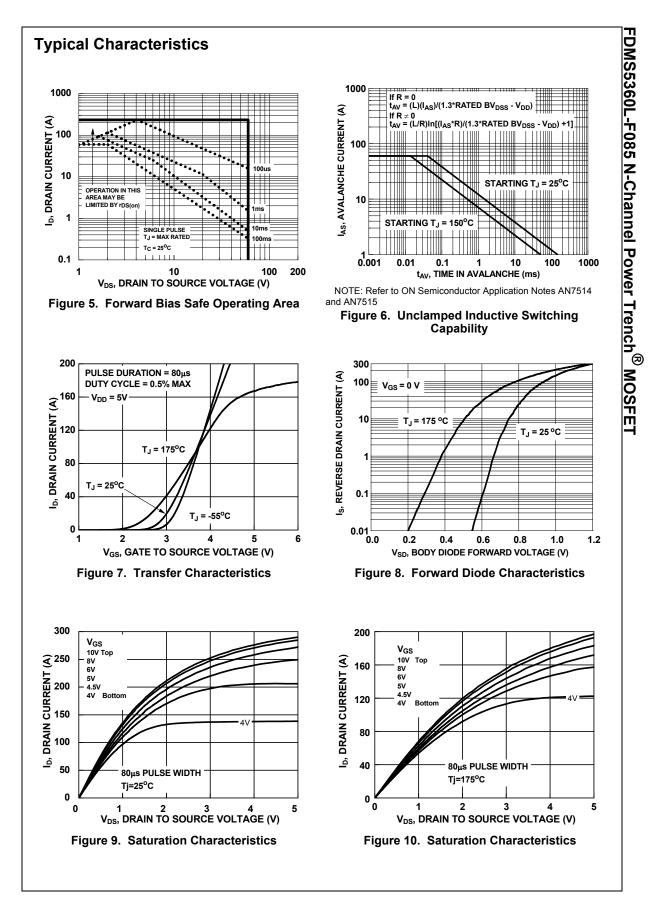
acteristics Drain to Source Breakdown Voltage Drain to Source Leakage Current	I _D = 250μA, V					Units
	I _D = 250μA, V					
Drain to Source Leakage Current		I _D = 250μA, V _{GS} = 0V		-	-	V
Drain to Source Leakage Current	V _{DS} =60V,	T _J = 25°C	-	-	1	μA
	$V_{GS} = 0V$	$T_J = 175^{\circ}C(Note 4)$	-	-	1	mA
Gate to Source Leakage Current	V_{GS} = ±20V		-	-	±100	nA
acteristics						
Gate to Source Threshold Voltage	V_{GS} = V_{DS} , I_{D}	, = 250μA	1.0	1.9	3.0	V
	I _D = 60A,	T _J = 25 ^o C	•	6.5	8.5	mΩ
Drain to Source On Resistance	V _{GS} = 10V	T _J = 175 ^o C(Note 4)	-	14.3	17.5	mΩ
	I _D = 60A,		-	8.7	10.5	mΩ
	V _{GS} = 4.5V	T _J = 175 ^o C(Note 4)	-	18.2	21.6	mΩ
Output Capacitance Reverse Transfer Capacitance	f = 1MHz		-	295	-	pF
				155	-	-
Gate Resistance	f = 1MHz		-	155 1.3	-	pF Ω
Gate Resistance Total Gate Charge at 10V		V V _{DD} = 48V	-			pF
	V _{GS} = 0 to 10			1.3	-	pF Ω
Total Gate Charge at 10V			-	1.3 64	- 72	pF Ω nC
	Gate to Source Threshold Voltage Drain to Source On Resistance Characteristics Input Capacitance Output Capacitance	Gate to Source Threshold Voltage $V_{GS} = V_{DS}$, I_D Drain to Source On Resistance $I_D = 60A$, $V_{GS} = 10V$ $I_D = 60A$, $V_{GS} = 4.5V$ Characteristics Input Capacitance Output Capacitance $V_{DS} = 30V$, V_{f} Output Capacitance	Gate to Source Threshold Voltage $V_{GS} = V_{DS}$, $I_D = 250 \mu A$ Drain to Source On Resistance $I_D = 60A$, $T_J = 25^{\circ}C$ $V_{GS} = 10V$ $T_J = 175^{\circ}C(Note 4)$ $I_D = 60A$, $T_J = 25^{\circ}C$ $V_{GS} = 4.5V$ $T_J = 175^{\circ}C(Note 4)$ CharacteristicsInput CapacitanceOutput Capacitance $V_{DS} = 30V, V_{GS} = 0V, f = 1MHz$	Gate to Source Threshold Voltage $V_{GS} = V_{DS}$, $I_D = 250\mu A$ 1.0 I_D = 60A, $T_J = 25^{\circ}C$ - $V_{GS} = 10V$ $T_J = 175^{\circ}C(Note 4)$ - $I_D = 60A$, $T_J = 25^{\circ}C$ - $V_{GS} = 4.5V$ $T_J = 175^{\circ}C(Note 4)$ -CharacteristicsInput Capacitance $V_{DS} = 30V$, $V_{GS} = 0V$,- $f = 1MH_Z$ -	Gate to Source Threshold Voltage $V_{GS} = V_{DS}$, $I_D = 250 \mu A$ 1.0 1.9 $I_D = 60A$, $V_{GS} = 10V$ $T_J = 25^{\circ}C$ - 6.5 $V_{GS} = 10V$ $T_J = 175^{\circ}C(Note 4)$ - 14.3 $I_D = 60A$, $V_{GS} = 4.5V$ $T_J = 25^{\circ}C$ - 8.7 Characteristics Input Capacitance V_{DS} = 30V, $V_{GS} = 0V$, - 3695 Output Capacitance V_{DS} = 30V, $V_{GS} = 0V$, - 295	Gate to Source Threshold Voltage $V_{GS} = V_{DS}$, $I_D = 250 \mu A$ 1.0 1.9 3.0 $I_D = 60A$, $V_{GS} = 10V$ $T_J = 25^{\circ}C$ - 6.5 8.5 $V_{GS} = 10V$ $T_J = 175^{\circ}C(Note 4)$ - 14.3 17.5 $I_D = 60A$, $V_{GS} = 4.5V$ $T_J = 25^{\circ}C$ - 8.7 10.5 Characteristics Input Capacitance V_{DS} = 30V, $V_{GS} = 0V$, - 3695 - Output Capacitance V_DS = 30V, $V_{GS} = 0V$, - 295 -

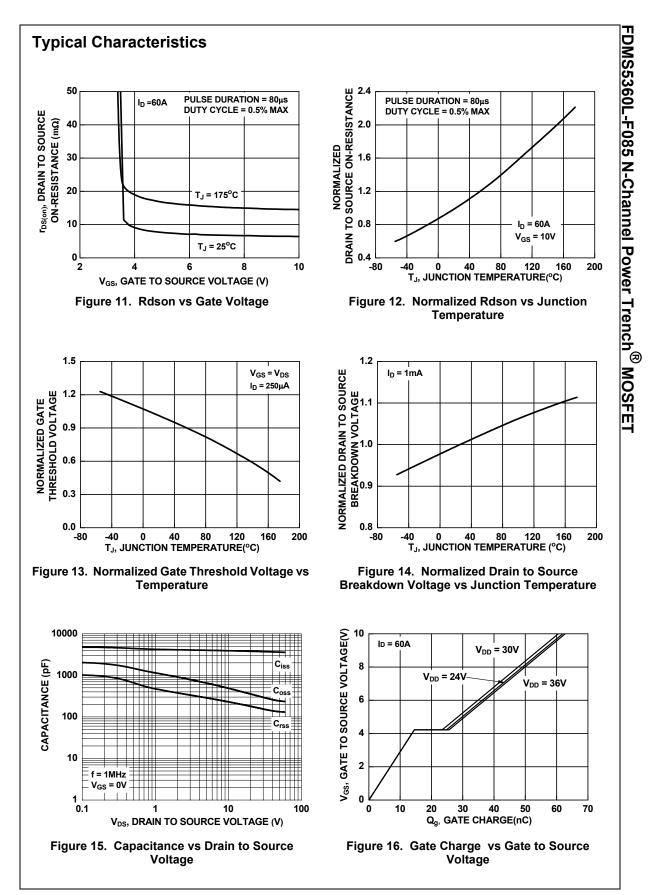
T_{rr} Reverse Recovery TimeIF = 60A, dI_{SD}/dt = 100A/ μ s,-3641ns Q_{rr} Reverse Recovery Charge V_{DD} =48V-3645nC	V_{SD}	Source to Drain Diode Voltage	I _{SD} = 60A, V _{GS} = 0V	-	-	1.25	V
Q _{rr} Reverse Recovery Charge V _{DD} =48V - 36 45 nC	T _{rr}	Reverse Recovery Time	I _F = 60A, dI _{SD} /dt = 100A/μs,	-	36	41	ns
	Q _{rr}	Reverse Recovery Charge	V _{DD} =48V	-	36	45	nC

Notes:

4: The maximum value is specified by design at T_J = 175°C. Product is not tested to this condition in production.







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